#### 502913798 07/30/2014

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2960396

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
CHIEN-WEI WANG	09/17/2013
CHING-YU CHANG	09/17/2013

### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. 6	
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	13942357

### CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2146515000

Email: IPDOCKETING@HAYNESBOONE.COM HAYNES AND BOONE, LLP - IP SECTION Correspondent Name:

Address Line 1: 2323 VICTORY AVENUE

Address Line 2: SUITE 700

Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	2009-0276-D/24061.2559	
NAME OF SUBMITTER:	LYDIA EPPS-HILLIARD	
SIGNATURE:	/Lydia Epps-Hilliard/	
DATE SIGNED:	07/30/2014	

**Total Attachments: 2** 

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> **PATENT** REEL: 033422 FRAME: 0238 502913798

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Docket No.: 2009-0276-D/24061.2559

Customer No.: 42717

### ASSIGNMENT

WHEREAS, we,

(1) Chien-Wei of No. 2, Alley 74, Lane 296, Minsheng Rd.

Wufong Township

Taichung County 413, Taiwan R.O.C.

(2) Ching-Yu Chang of No. 17, Hsinchen Road

Yuansun Village

Yilang County, Taiwan 264

have invented certain improvements in

## PHOTORESIST STRIPPING TECHNIQUE

for which we have executed an application for Letters Patent of the United States of America, filed on <u>July 15</u>, 2013, and assigned application number <u>13/942,357</u>; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths

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and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Chien- Wei Wang

Residence Address:

No. 2, Alley 74, Lane 296, Minsheng Rd.

Wufong Township

Taichung County 413, Taiwan R.O.C.

Dated: 2013, 9,17

Inventor Signature

Inventor Name:

Ching-Yu Chang

Residence Address:

No. 17, Hsinchen Road

Yuansun Village

Yilang County, Taiwan 264

Dated: >013 9, 17

Inventor Signature

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PATENT REEL: 033422 FRAME: 0240